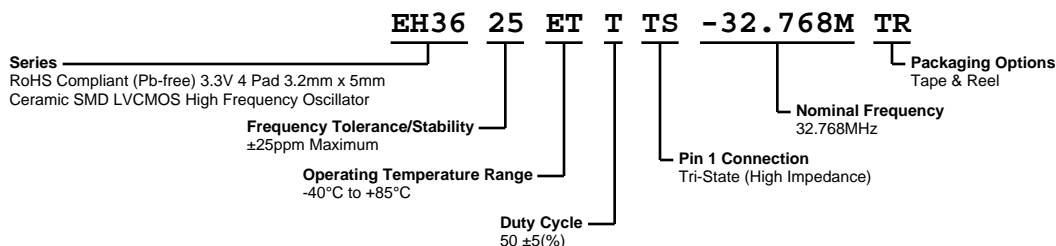


EH3625ETTS-32.768M TR



ECLIPTEK®
CORPORATION



ELECTRICAL SPECIFICATIONS

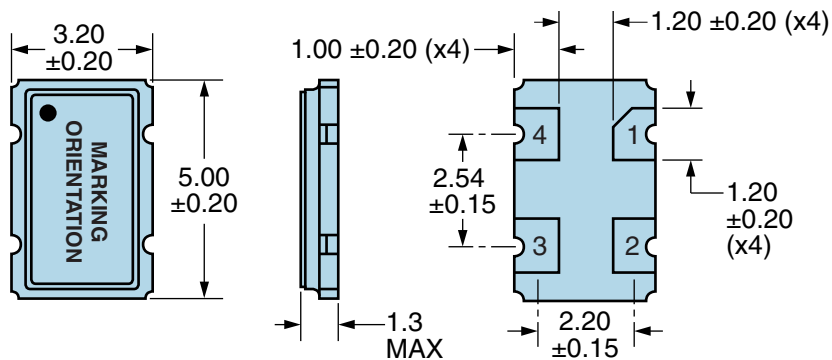
| | |
|---------------------------------------|--|
| Nominal Frequency | 32.768MHz |
| Frequency Tolerance/Stability | ±25ppm Maximum (Inclusive of all conditions: Calibration Tolerance at 25°C, Frequency Stability over the Operating Temperature Range, Supply Voltage Change, Output Load Change, 1st Year Aging at 25°C, Shock, and Vibration) |
| Aging at 25°C | ±5ppm/year Maximum |
| Operating Temperature Range | -40°C to +85°C |
| Supply Voltage | 3.3Vdc ±0.3Vdc |
| Input Current | 35mA Maximum (No Load) |
| Output Voltage Logic High (Voh) | 2.7Vdc Minimum (IOH = -8mA) |
| Output Voltage Logic Low (Vol) | 0.5Vdc Maximum (IOL = +8mA) |
| Rise/Fall Time | 6nSec Maximum (Measured at 20% to 80% of waveform) |
| Duty Cycle | 50 ±5(%) (Measured at 50% of waveform) |
| Load Drive Capability | 30pF Maximum |
| Output Logic Type | CMOS |
| Pin 1 Connection | Tri-State (High Impedance) |
| Tri-State Input Voltage (Vih and Vil) | 70% of Vdd Minimum to enable output, 20% of Vdd Maximum to disable output, No Connect to enable output. |
| Absolute Clock Jitter | ±250pSec Maximum, ±100pSec Typical |
| One Sigma Clock Period Jitter | ±50pSec Maximum, ±40pSec Typical |
| Start Up Time | 10mSec Maximum |
| Storage Temperature Range | -55°C to +125°C |

ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

| | |
|------------------------------|---------------------------------------|
| Fine Leak Test | MIL-STD-883, Method 1014, Condition A |
| Gross Leak Test | MIL-STD-883, Method 1014, Condition C |
| Mechanical Shock | MIL-STD-202, Method 213, Condition C |
| Resistance to Soldering Heat | MIL-STD-202, Method 210 |
| Resistance to Solvents | MIL-STD-202, Method 215 |
| Solderability | MIL-STD-883, Method 2003 |
| Temperature Cycling | MIL-STD-883, Method 1010 |
| Vibration | MIL-STD-883, Method 2007, Condition A |

EH3625ETTTTS-32.768M TR

MECHANICAL DIMENSIONS (all dimensions in millimeters)

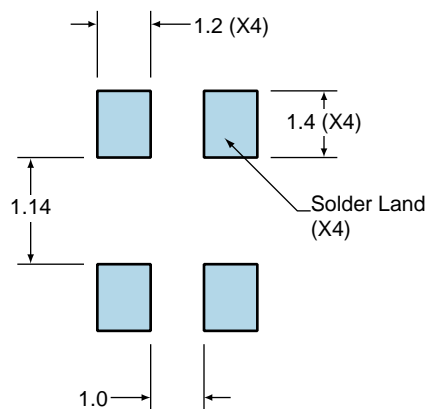


| PIN | CONNECTION |
|-----|--------------------|
| 1 | Tri-State |
| 2 | Ground/Case Ground |
| 3 | Output |
| 4 | Supply Voltage |

| LINE | MARKING |
|------|--|
| 1 | E32.768 <i>E=Ecliptek Designator</i> |

Suggested Solder Pad Layout

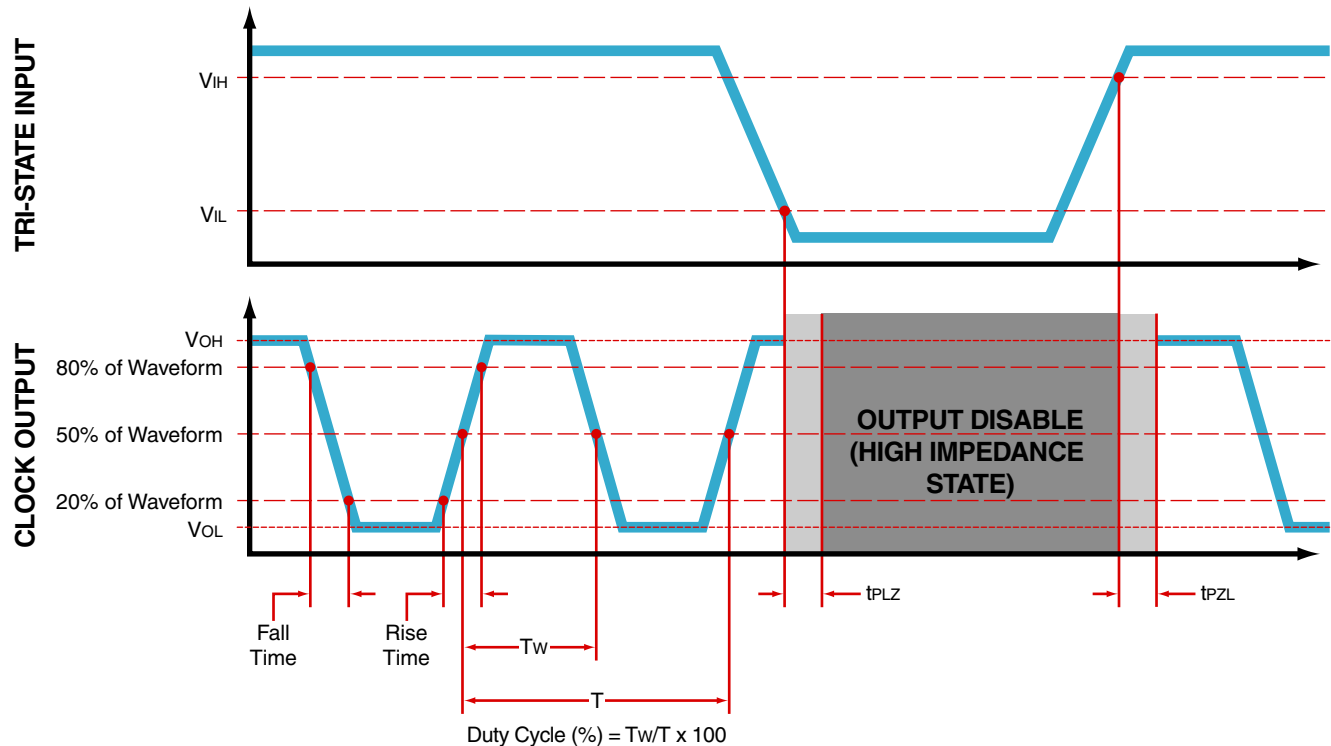
All Dimensions in Millimeters



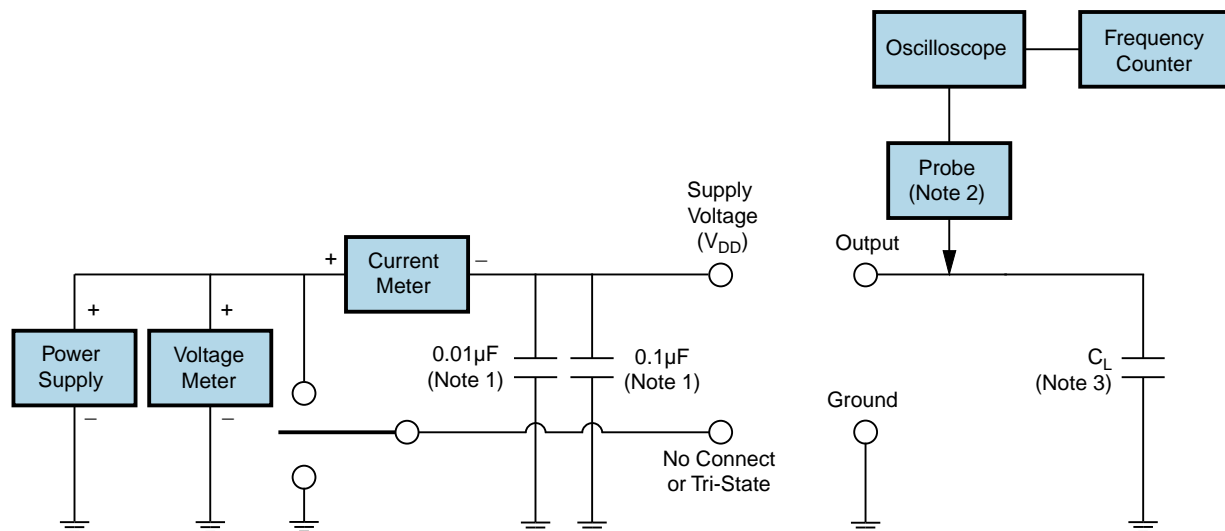
All Tolerances are ± 0.1

EH3625ETTS-32.768M TR

OUTPUT WAVEFORM & TIMING DIAGRAM



Test Circuit for CMOS Output

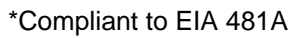


Note 1: An external 0.1μF low frequency tantalum bypass capacitor in parallel with a 0.01μF high frequency ceramic bypass capacitor close to the package ground and V_{DD} pin is required.

Note 2: A low capacitance (<12pF), 10X attenuation factor, high impedance (>10Mohms), and high bandwidth (>300MHz) passive probe is recommended.

Note 3: Capacitance value C_L includes sum of all probe and fixture capacitance.

Quantity Per Reel: 1,000 units



Recommended Solder Reflow Methods



High Temperature Infrared/Convection

T_s MAX to T_L (Ramp-up Rate) 3°C/second Maximum

Preheat

- Temperature Minimum (T_s MIN) 150°C
- Temperature Typical (T_s TYP) 175°C
- Temperature Maximum (T_s MAX) 200°C
- Time (t_s MIN) 60 - 180 Seconds

Ramp-up Rate (T_L to T_p) 3°C/second Maximum

Time Maintained Above:

- Temperature (T_L) 217°C
- Time (t_L) 60 - 150 Seconds

Peak Temperature (T_p) 260°C Maximum for 10 Seconds Maximum

Target Peak Temperature (T_p Target) 250°C +0/-5°C

Time within 5°C of actual peak (t_p) 20 - 40 seconds

Ramp-down Rate 6°C/second Maximum

Time 25°C to Peak Temperature (t) 8 minutes Maximum

Moisture Sensitivity Level Level 1

Recommended Solder Reflow Methods



Low Temperature Infrared/Convection 240°C

T_S MAX to T_L (Ramp-up Rate) 5°C/second Maximum

Preheat

- Temperature Minimum (T_S MIN) N/A
 - Temperature Typical (T_S TYP) 150°C
 - Temperature Maximum (T_S MAX) N/A
 - Time (t_S MIN) 60 - 120 Seconds

Ramp-up Rate (T_L to T_P) 5°C/second Maximum

Time Maintained Above:

- Temperature (T_L) 150°C
 - Time (t_L) 200 Seconds Maximum

Peak Temperature (T_P) 240°C Maximum

Target Peak Temperature (T_P Target) 240°C Maximum 1 Time / 230°C Maximum 2 Times

Time within 5°C of actual peak (t_p) 10 seconds Maximum 2 Times / 80 seconds Maximum 1 Time

Ramp-down Rate 5°C/second Maximum

Time 25°C to Peak Temperature (t) N/A

Moisture Sensitivity Level Level 1

Low Temperature Manual Soldering

185°C Maximum for 10 seconds Maximum, 2 times Maximum.

High Temperature Manual Soldering

260°C Maximum for 5 seconds Maximum, 2 times Maximum.